



IMPORTANT NOTICE

10 December 2015

1. Global joint venture starts operations as WeEn Semiconductors

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WeEn Semiconductors





BT149G

SCR

13 March 2014

Product data sheet

1. General description

Planar passivated Silicon Controlled Rectifier with sensitive gate in a SOT54 (TO-92) plastic package. This SCR is designed to be interfaced directly to microcontrollers, logic ICs and other low power gate trigger circuits.

2. Features and benefits

- Enhanced voltage capability
- Planar passivated for voltage ruggedness and reliability
- Sensitive gate
- Direct triggering from low power drivers and logic ICs

3. Applications

- General purpose switching and phase control

4. Quick reference data

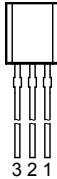

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|--------------------------------------|--|-----|-----|-----|---------------|
| V_{DRM} | repetitive peak off-state voltage | | - | - | 600 | V |
| V_{RRM} | repetitive peak reverse voltage | | - | - | 600 | V |
| I_{TSM} | non-repetitive peak on-state current | half sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5 | - | - | 8 | A |
| $I_{T(AV)}$ | average on-state current | half sine wave; $T_{lead} \leq 83\text{ }^{\circ}\text{C}$; Fig. 1 | - | - | 0.5 | A |
| $I_{T(RMS)}$ | RMS on-state current | half sine wave; $T_{lead} \leq 83\text{ }^{\circ}\text{C}$; Fig. 2 ; Fig. 3 | - | - | 0.8 | A |
| Static characteristics | | | | | | |
| I_{GT} | gate trigger current | $V_D = 12\text{ V}$; $I_T = 10\text{ mA}$; $T_j = 25\text{ }^{\circ}\text{C}$; Fig. 7 | - | 50 | 200 | μA |



5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|--|---|
| 1 | K | cathode |  <p>TO-92 (SOT54)</p> |  |
| 2 | G | gate | | |
| 3 | A | anode | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|---------|---|---------|
| | Name | Description | Version |
| BT149G | TO-92 | plastic single-ended leaded (through hole) package; 3 leads | SOT54 |

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|--------------|--------------------------------------|--|-----|------|------------------------|
| V_{DRM} | repetitive peak off-state voltage | | - | 600 | V |
| V_{RRM} | repetitive peak reverse voltage | | - | 600 | V |
| $I_{T(AV)}$ | average on-state current | half sine wave; $T_{lead} \leq 83\text{ }^{\circ}\text{C}$; Fig. 1 | - | 0.5 | A |
| $I_{T(RMS)}$ | RMS on-state current | half sine wave; $T_{lead} \leq 83\text{ }^{\circ}\text{C}$; Fig. 2 ; Fig. 3 | - | 0.8 | A |
| I_{TSM} | non-repetitive peak on-state current | half sine wave; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5 | - | 8 | A |
| | | half sine wave; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; $t_p = 8.3\text{ ms}$ | - | 9 | A |
| I^2t | I^2t for fusing | $t_p = 10\text{ ms}$; SIN | - | 0.32 | A^2s |
| di_T/dt | rate of rise of on-state current | $I_T = 2\text{ A}$; $I_G = 10\text{ mA}$; $di_G/dt = 100\text{ mA}/\mu\text{s}$ | - | 50 | $\text{A}/\mu\text{s}$ |
| I_{GM} | peak gate current | | - | 1 | A |
| V_{RGM} | peak reverse gate voltage | | - | 5 | V |
| P_{GM} | peak gate power | | - | 2 | W |
| $P_{G(AV)}$ | average gate power | over any 20 ms period | - | 0.1 | W |
| T_{stg} | storage temperature | | -40 | 150 | $^{\circ}\text{C}$ |
| T_j | junction temperature | | - | 125 | $^{\circ}\text{C}$ |

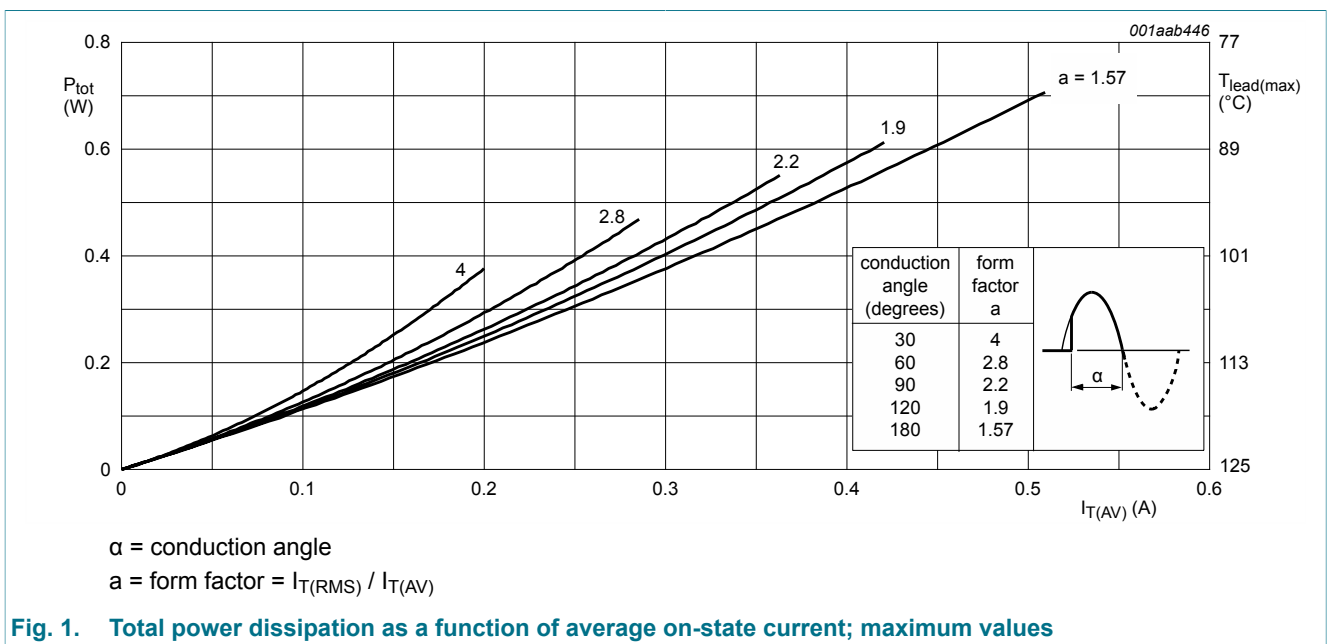
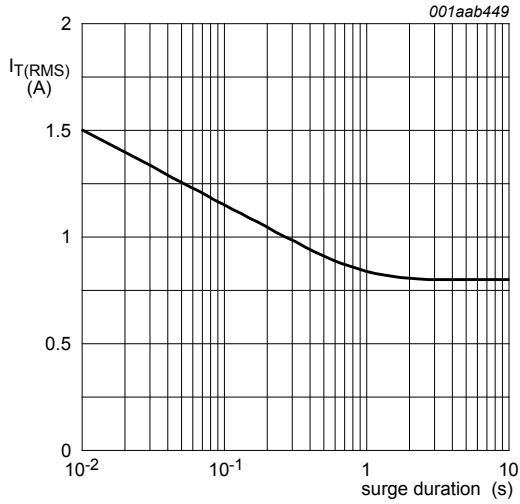


Fig. 1. Total power dissipation as a function of average on-state current; maximum values



$f = 50 \text{ Hz}; T_{\text{lead}} = 83 \text{ }^\circ\text{C}$

Fig. 2. RMS on-state current as a function of surge duration for sinusoidal currents

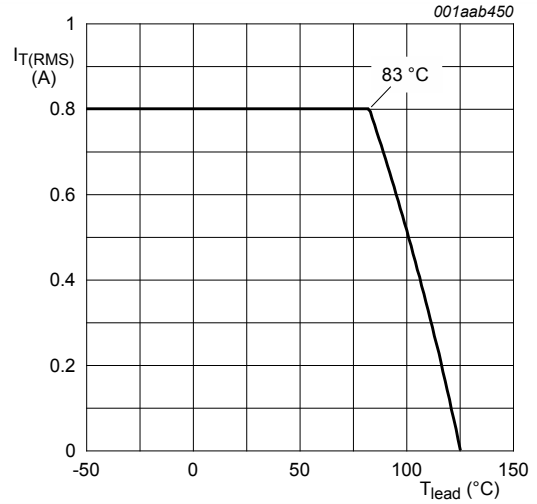
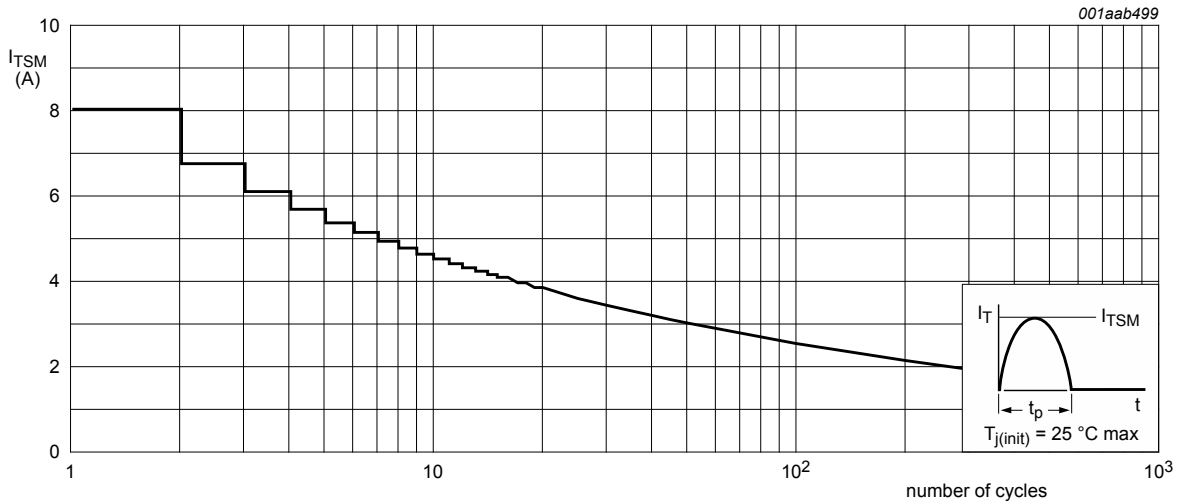
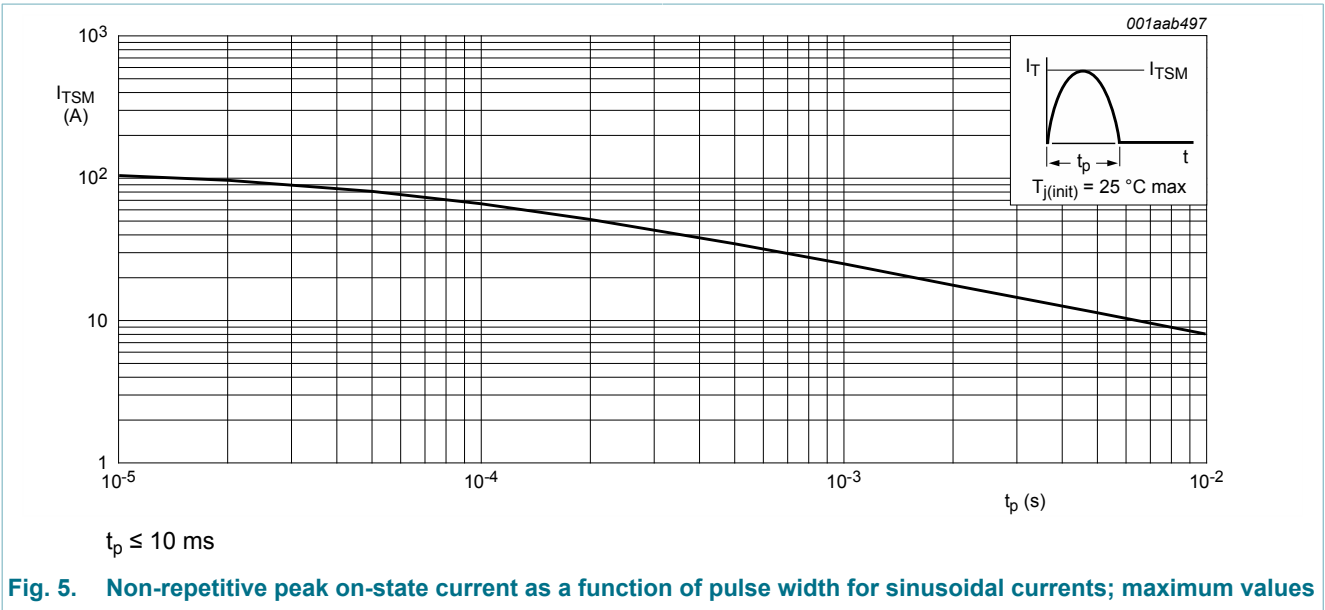


Fig. 3. RMS on-state current as a function of lead temperature; maximum values



$f = 50 \text{ Hz}$

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



8. Thermal characteristics

Table 5. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|---|---|-----|-----|-----|------|
| $R_{th(j-lead)}$ | thermal resistance from junction to lead | Fig. 6 | - | - | 60 | K/W |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | printed circuit board mounted: lead length = 4 mm | - | 150 | - | K/W |

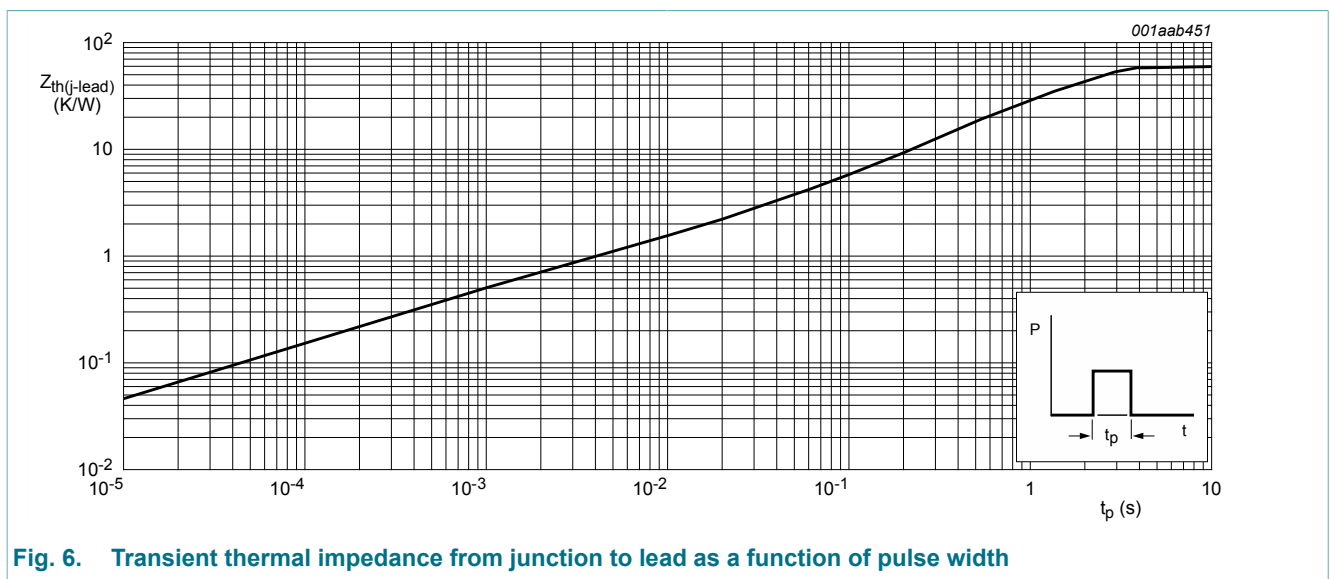


Fig. 6. Transient thermal impedance from junction to lead as a function of pulse width

9. Characteristics

Table 6. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|-----------------------------------|--|-----|------|-----|------------------------|
| Static characteristics | | | | | | |
| I_{GT} | gate trigger current | $V_D = 12\text{ V}$; $I_T = 10\text{ mA}$; $T_j = 25\text{ °C}$; Fig. 7 | - | 50 | 200 | μA |
| I_L | latching current | $V_D = 12\text{ V}$; $I_G = 0.5\text{ mA}$; $R_{GK} = 1\text{ k}\Omega$; $T_j = 25\text{ °C}$; Fig. 8 | - | 2 | 6 | mA |
| I_H | holding current | $V_D = 12\text{ V}$; $R_{GK} = 1\text{ k}\Omega$; $T_j = 25\text{ °C}$; Fig. 9 | - | 2 | 5 | mA |
| V_T | on-state voltage | $I_T = 1.2\text{ A}$; $T_j = 25\text{ °C}$; Fig. 10 | - | 1.25 | 1.7 | V |
| V_{GT} | gate trigger voltage | $V_D = 12\text{ V}$; $I_T = 10\text{ mA}$; $T_j = 25\text{ °C}$; Fig. 11 | - | 0.5 | 0.8 | V |
| | | $V_D = 600\text{ V}$; $I_T = 10\text{ mA}$; $T_j = 125\text{ °C}$; Fig. 11 | 0.2 | 0.3 | - | V |
| I_D | off-state current | $V_D = 600\text{ V}$; $T_j = 125\text{ °C}$; $R_{GK} = 1\text{ k}\Omega$ | - | 0.05 | 0.1 | mA |
| I_R | reverse current | $V_R = 600\text{ V}$; $T_j = 125\text{ °C}$; $R_{GK} = 1\text{ k}\Omega$ | - | 0.05 | 0.1 | mA |
| Dynamic characteristics | | | | | | |
| dV_D/dt | rate of rise of off-state voltage | $V_{DM} = 402\text{ V}$; $T_j = 125\text{ °C}$; $R_{GK} = 1\text{ k}\Omega$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; Fig. 12 | 500 | 800 | - | $\text{V}/\mu\text{s}$ |
| | | $V_{DM} = 402\text{ V}$; $T_j = 125\text{ °C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit; Fig. 12 | - | 2 | - | $\text{V}/\mu\text{s}$ |
| t_{gt} | gate-controlled turn-on time | $I_{TM} = 2\text{ A}$; $V_D = 600\text{ V}$; $I_G = 10\text{ mA}$; $dI_G/dt = 0.1\text{ A}/\mu\text{s}$; $T_j = 25\text{ °C}$ | - | 2 | - | μs |
| t_q | commutated turn-off time | $V_{DM} = 402\text{ V}$; $T_j = 125\text{ °C}$; $I_{TM} = 1.6\text{ A}$; $V_R = 35\text{ V}$; $(dI_T/dt)_M = 30\text{ A}/\mu\text{s}$; $dV_D/dt = 2\text{ V}/\mu\text{s}$; $R_{GK} = 1\text{ k}\Omega$; ($V_{DM} = 67\%$ of V_{DRM}) | - | 100 | - | μs |

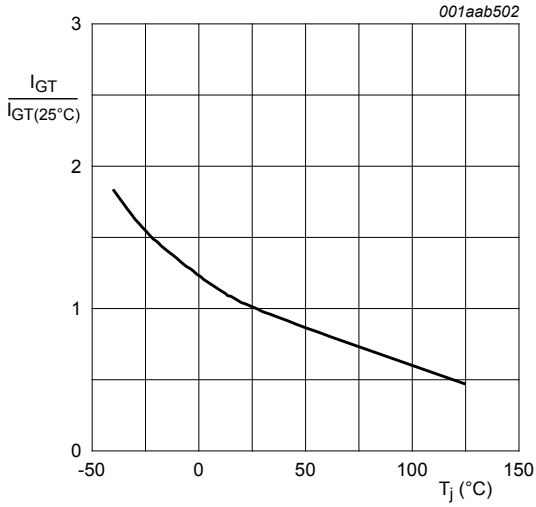
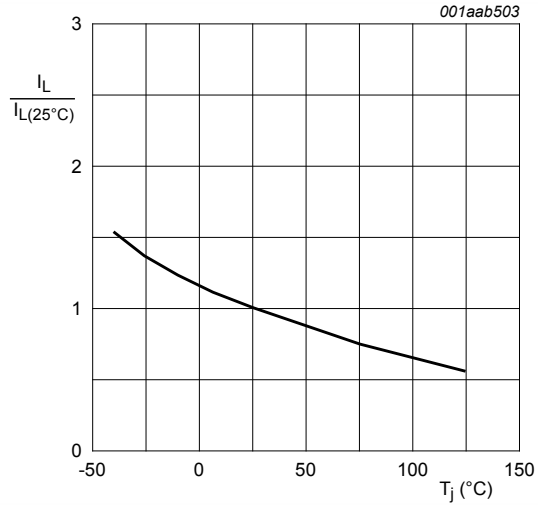
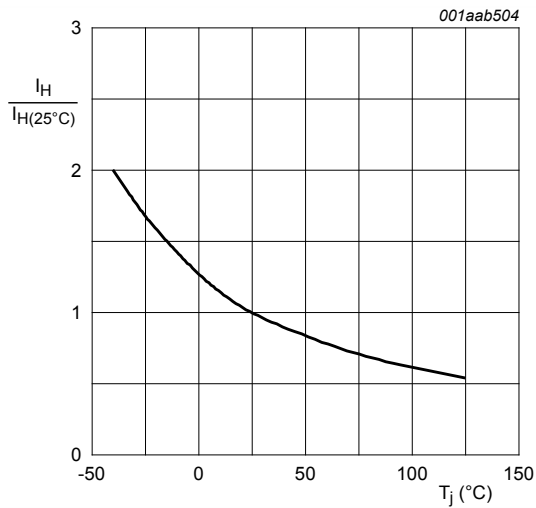


Fig. 7. Normalized gate trigger current as a function of junction temperature



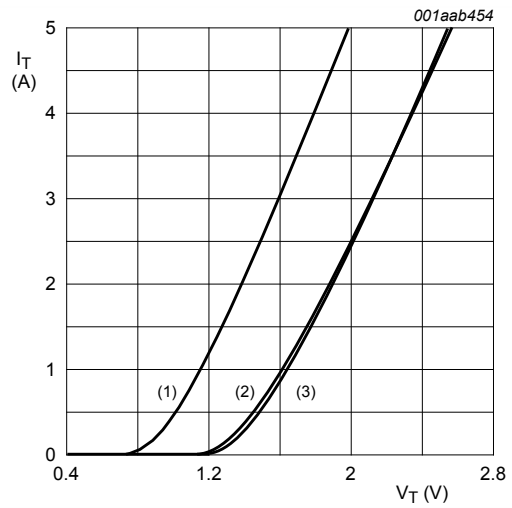
$R_{GK} = 1 \text{ k}\Omega$

Fig. 8. Normalized latching current as a function of junction temperature



$R_{GK} = 1 \text{ k}\Omega$

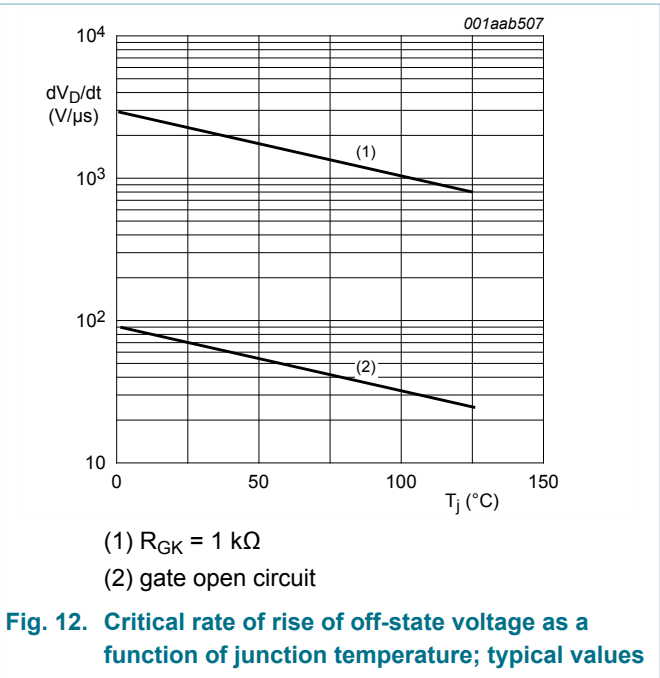
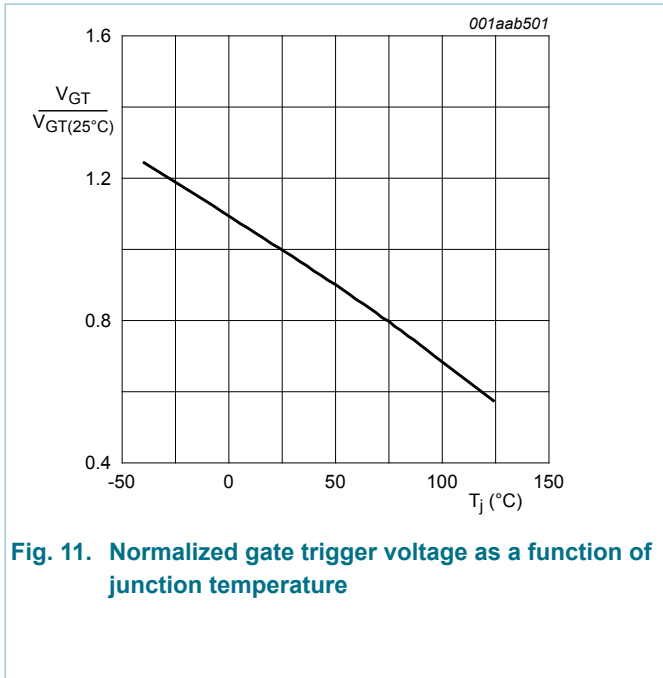
Fig. 9. Normalized holding current as a function of junction temperature



$V_o = 1.067 \text{ V}; R_s = 0.187 \Omega$

- (1) $T_j = 125 \text{ }^\circ\text{C}$; typical values
- (2) $T_j = 125 \text{ }^\circ\text{C}$; maximum values
- (3) $T_j = 25 \text{ }^\circ\text{C}$; maximum values

Fig. 10. On-state current as a function of on-state voltage



10. Package outline

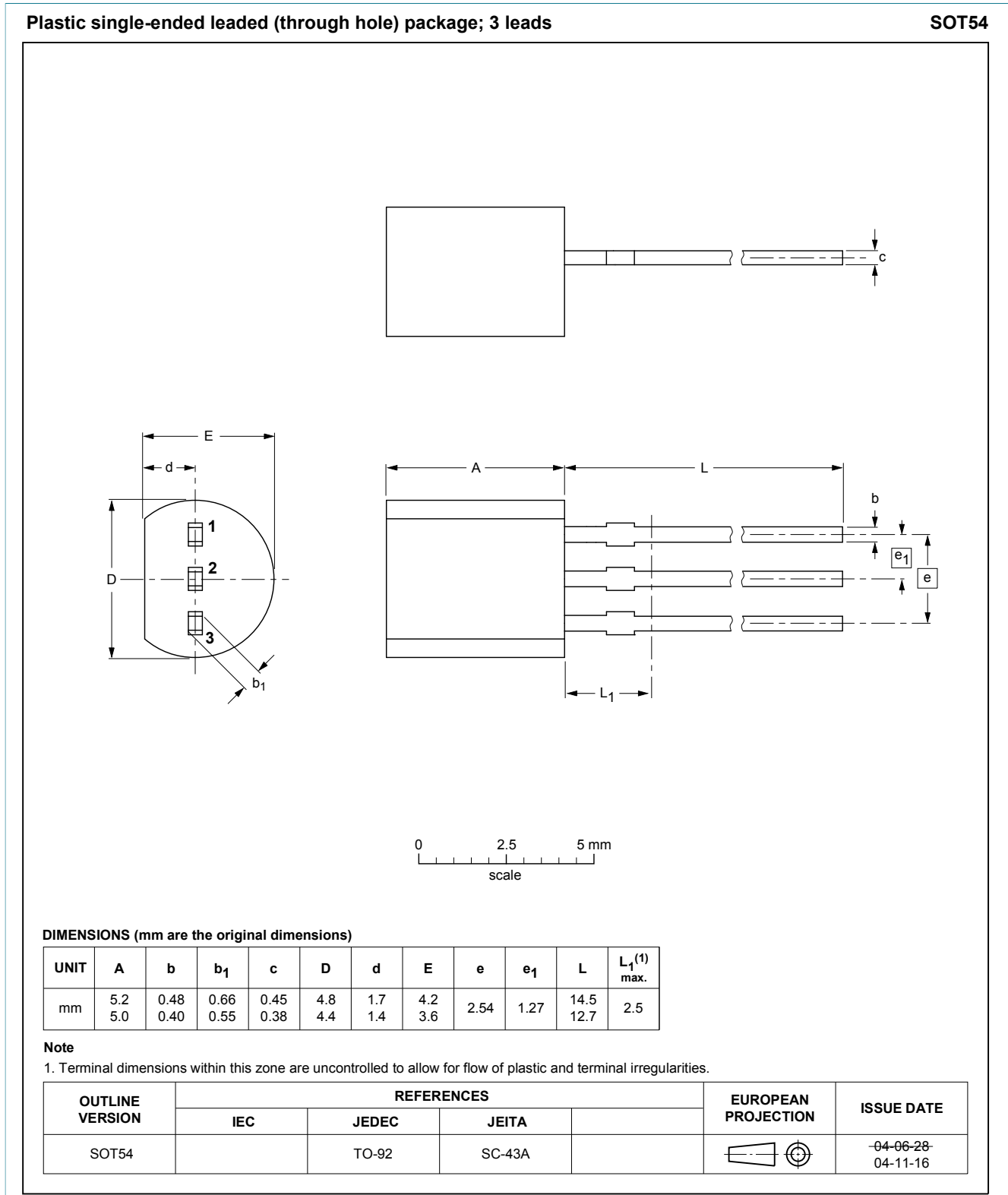


Fig. 13. Package outline TO-92 (SOT54)

11. Legal information

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|--------------------------------|--------------------|---|
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| Product [short] data sheet | Production | This document contains the product specification. |

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